

Product / Process Change Notification



N° 2020-174-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Replacement of thin wire (50µm) incl. polished DCB by standard (300µm) wire bond incl. non polished DCB for Easy modules 600/650V smaller 30A

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **3 March 2021**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
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► **Products affected:** Please refer to affected product list 1_cip20174_A

► **Detailed Change Information:**

Subject: Phase-out thin wire and replace with standard gate wires by using IGBTs with larger gatepads

Reason: Standardization of bond wire process following Infineon's strategy to further ensure our product performance.

Description:

<u>Old</u>	<u>New</u>
■ Polished DCB	■ Standard DCB
■ IGBT chip with small gatepad	■ IGBT chip with larger gatepad
■ 50µm + 300µm wire bond	■ Only 300µm wire bond
■ SP001000984	■ SP005407477

► **Product Identification:** New MA number
Partially change in SP ordering number.

► **Impact of Change:** No impact on electrical performance. There is no change in form, fit and function.

► **Attachments:** Affected product list 1_cip20174_A

► **Time Schedule:**

- Final qualification report: available
- First samples available: available
- Intended start of delivery: 20 April 2021 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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incl. non polished DCB for Easy modules 600/650V smaller 30A



Sales name	SP number	OPN	Package
FB20R06W1E3	SP000307555	FB20R06W1E3BOMA1	AG-EASY1B
FB20R06W1E3_B11	SP001000984	FB20R06W1E3B11HOMA1	AG-EASY1B
FP10R06W1E3	SP000092044	FP10R06W1E3BOMA1	AG-EASY1B
FP10R06W1E3_B11	SP000790734	FP10R06W1E3B11BOMA1	AG-EASY1B
FP15R06W1E3	SP000092046	FP15R06W1E3BOMA1	AG-EASY1B
FP15R06W1E3_B11	SP000790730	FP15R06W1E3B11BOMA1	AG-EASY1B
FP15R06YE3_B4	SP000092051	FP15R06YE3B4BOMA1	AG-EASY2
FP20R06W1E3	SP000092041	FP20R06W1E3BOMA1	AG-EASY1B
FP20R06W1E3_B11	SP000790726	FP20R06W1E3B11BOMA1	AG-EASY1B
FP20R06YE3_B4	SP000089810	FP20R06YE3B4BOMA1	AG-EASY2
FS10R06VE3	SP000100333	FS10R06VE3BOMA1	AG-EASY750
FS10R06VE3_B2	SP000100311	FS10R06VE3B2BOMA1	AG-EASY750
FS15R06VE3_B2	SP000100312	FS15R06VE3B2BOMA1	AG-EASY750
FS15R06XE3	SP000100341	FS15R06XE3BOMA1	AG-EASY1
FS20R06VE3	SP000100335	FS20R06VE3BOMA1	AG-EASY750
FS20R06VE3_B2	SP000100313	FS20R06VE3B2BOMA1	AG-EASY750
FS20R06W1E3	SP000223651	FS20R06W1E3BOMA1	AG-EASY1B
FS20R06W1E3_B11	SP000790748	FS20R06W1E3B11BOMA1	AG-EASY1B
FS20R06XE3	SP000100342	FS20R06XE3BOMA1	AG-EASY1